US00D689829S

(12) **United States Design Patent**
Chen et al.

(10) **Patent No.: US D689,829 S**
(45) **Date of Patent: ** Sep. 17, 2013**

(54) **HEAT DISSIPATING MODULE OF MEMORY**

(71) Applicant: **CompTake Technology Inc.**, New Taipei (TW)

(72) Inventors: **Wei-Hau Chen**, New Taipei (TW);
Chia-Yuan Ku, New Taipei (TW);
Li-Hsu Chen, New Taipei (TW);
Hsin-An Chen, New Taipei (TW)

(73) Assignee: **CompTake Technology Inc.**, New Taipei (TW)

(**) Term: **14 Years**

(21) Appl. No.: **29/441,181**

(22) Filed: **Jan. 2, 2013**

(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/179**

(58) **Field of Classification Search**
USPC D13/179; 165/80.3, 104.26, 104.33, 165/122, 151, 185; 257/706, 707, 718–722; 361/679.54, 695, 697, 700, 702, 704, 707, 361/709, 710, 711, 715, 719
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

6,377,460	B1 *	4/2002	Pohl et al.	361/704
7,215,551	B2 *	5/2007	Wang et al.	361/707
7,221,569	B2 *	5/2007	Tsai	361/704
7,312,996	B2 *	12/2007	Chang	361/704
7,391,613	B2 *	6/2008	Lai et al.	361/700
7,447,024	B1 *	11/2008	Chou	361/695
7,457,122	B2 *	11/2008	Lai et al.	361/704
D597,966	S *	8/2009	Shih	D13/179
7,606,035	B2 *	10/2009	Park et al.	361/715
D609,199	S *	2/2010	Chen et al.	D13/179
7,738,252	B2 *	6/2010	Schuette et al.	361/704
7,768,785	B2 *	8/2010	Ni et al.	361/715
7,839,643	B1 *	11/2010	Yu	361/715
D657,756	S *	4/2012	Mueller	D13/179
8,411,443	B2 *	4/2013	Chen et al.	361/719
2003/0026076	A1 *	2/2003	Wei	361/704
2009/0122481	A1 *	5/2009	Chang et al.	361/679.54

* cited by examiner

Primary Examiner — Selina Sikder

(74) *Attorney, Agent, or Firm* — Chun-Ming Shih; HDLS IPR Services

(57) **CLAIM**

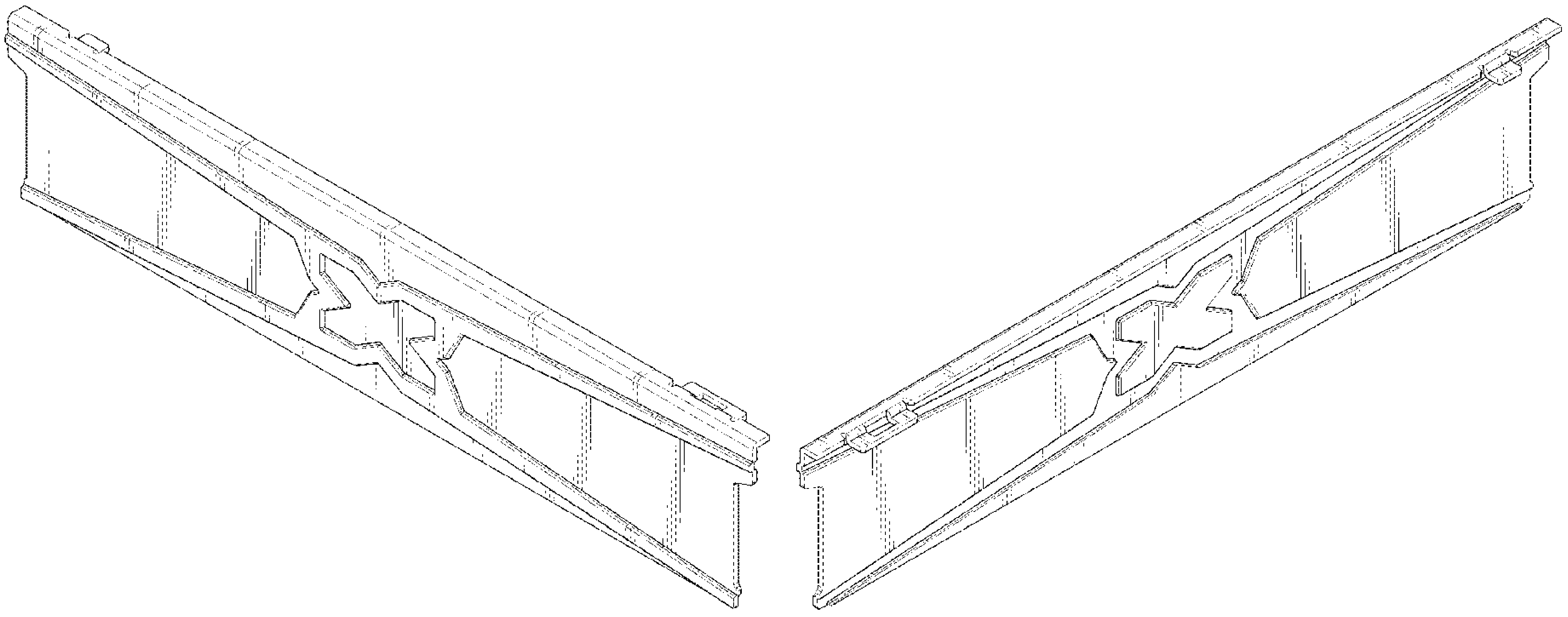
The ornamental design for a heat dissipating module of memory, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a heat dissipating module of memory showing our new design;
FIG. **2** is a front view thereof;
FIG. **3** is a rear view thereof;
FIG. **4** is a left side view thereof;
FIG. **5** is a right side view thereof;
FIG. **6** is a top view thereof;
FIG. **7** is a bottom view thereof; and
FIG. **8** is the other perspective view showing the heat dissipating module of memory; and,
FIG. **9** is a perspective view of the heat dissipating module of memory for reference.

The broken lines shown represent unclaimed subject matter and form no part of the claimed design.

1 Claim, 7 Drawing Sheets



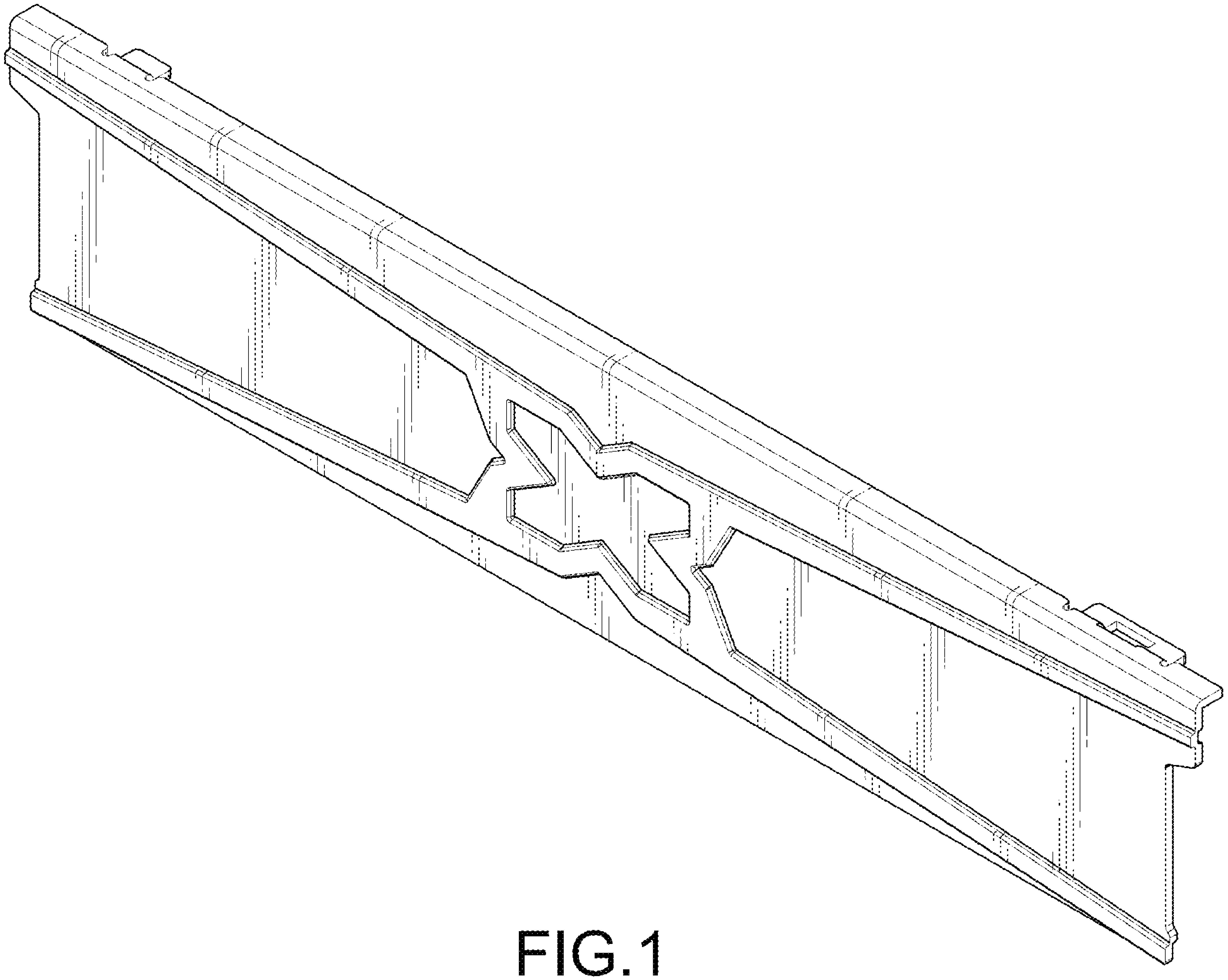


FIG.1

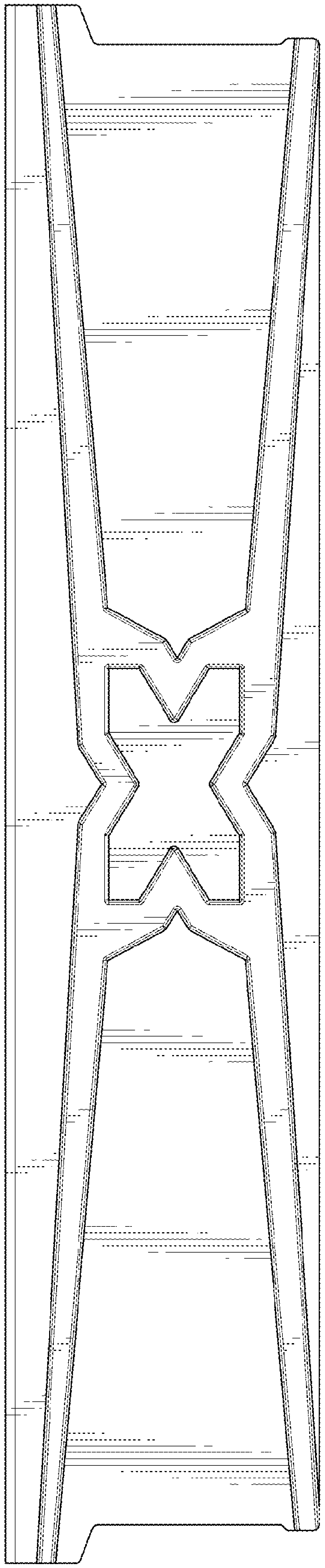


FIG.2

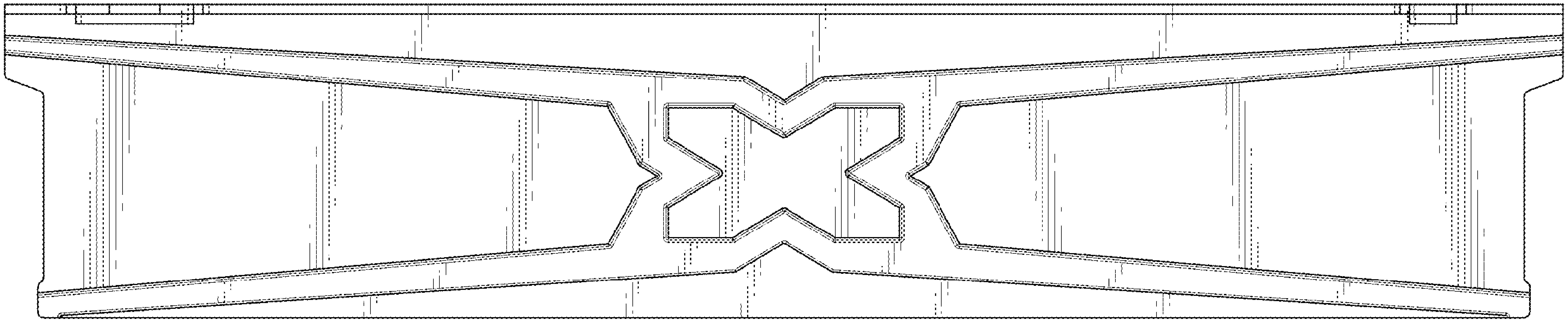


FIG.3

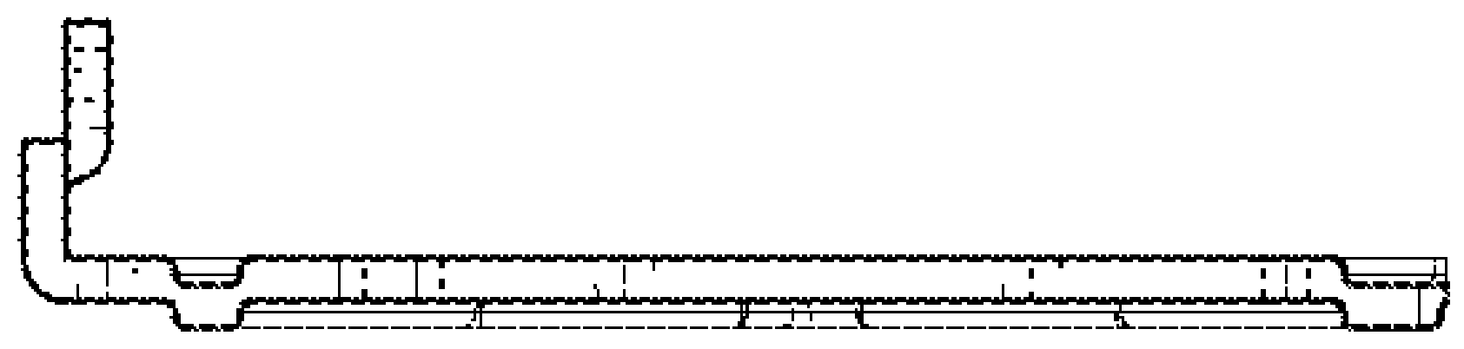


FIG.5

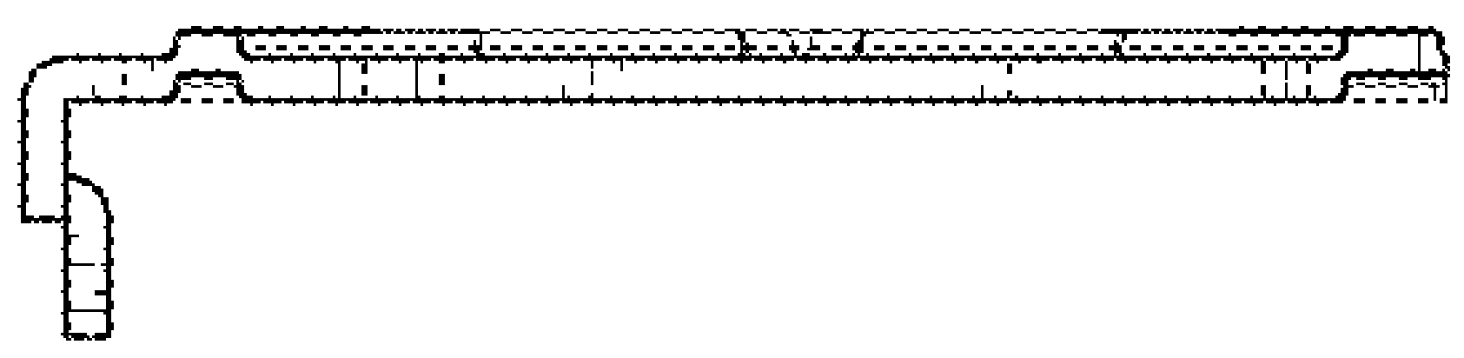


FIG.4

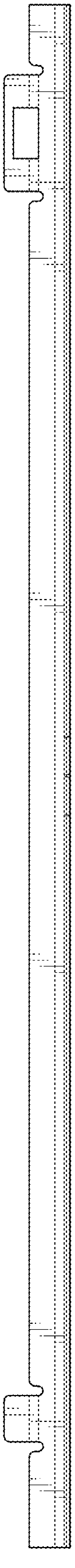


FIG.6

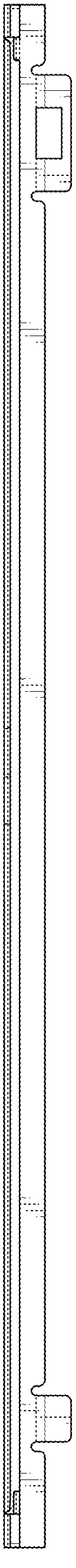


FIG.7

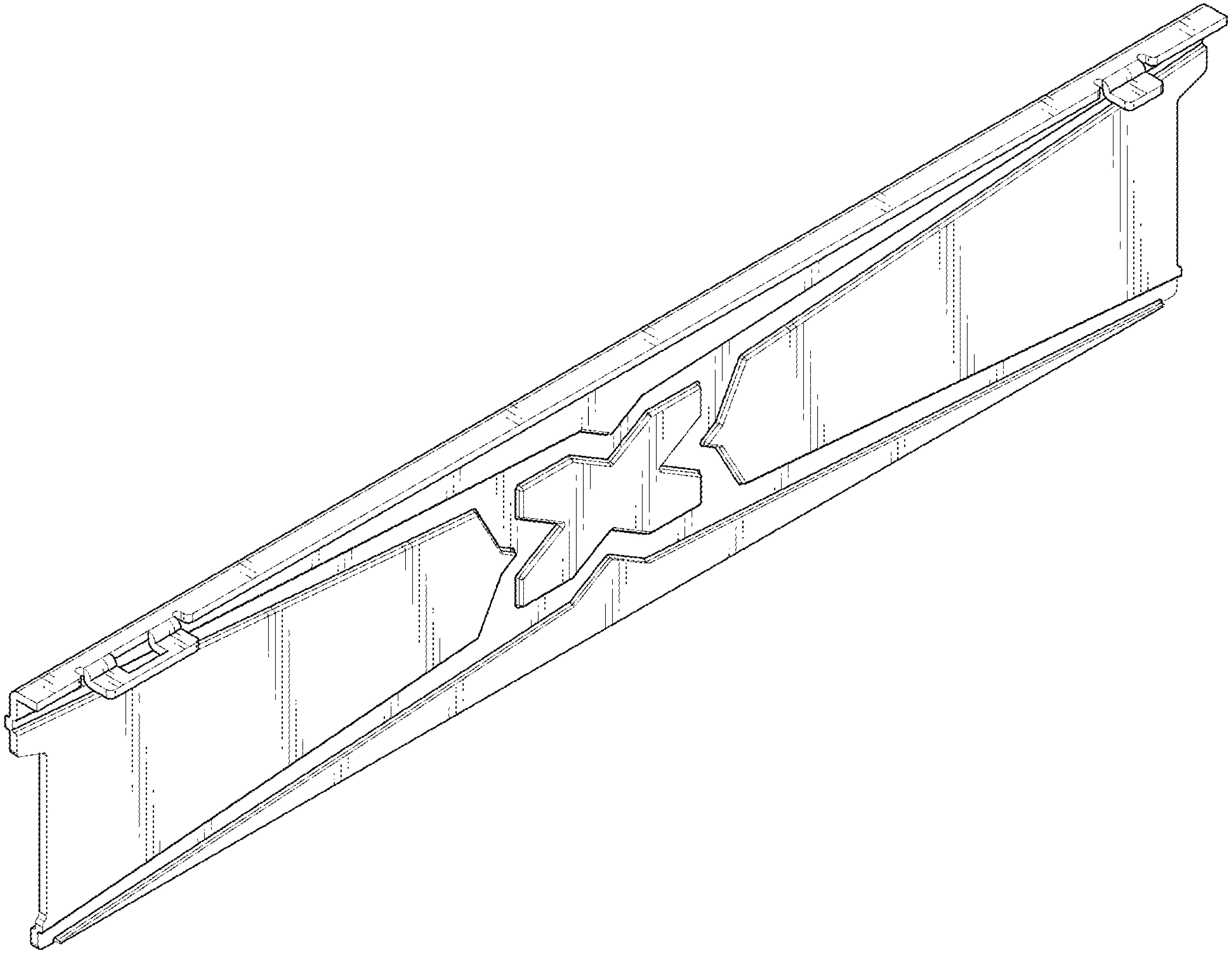


FIG.8

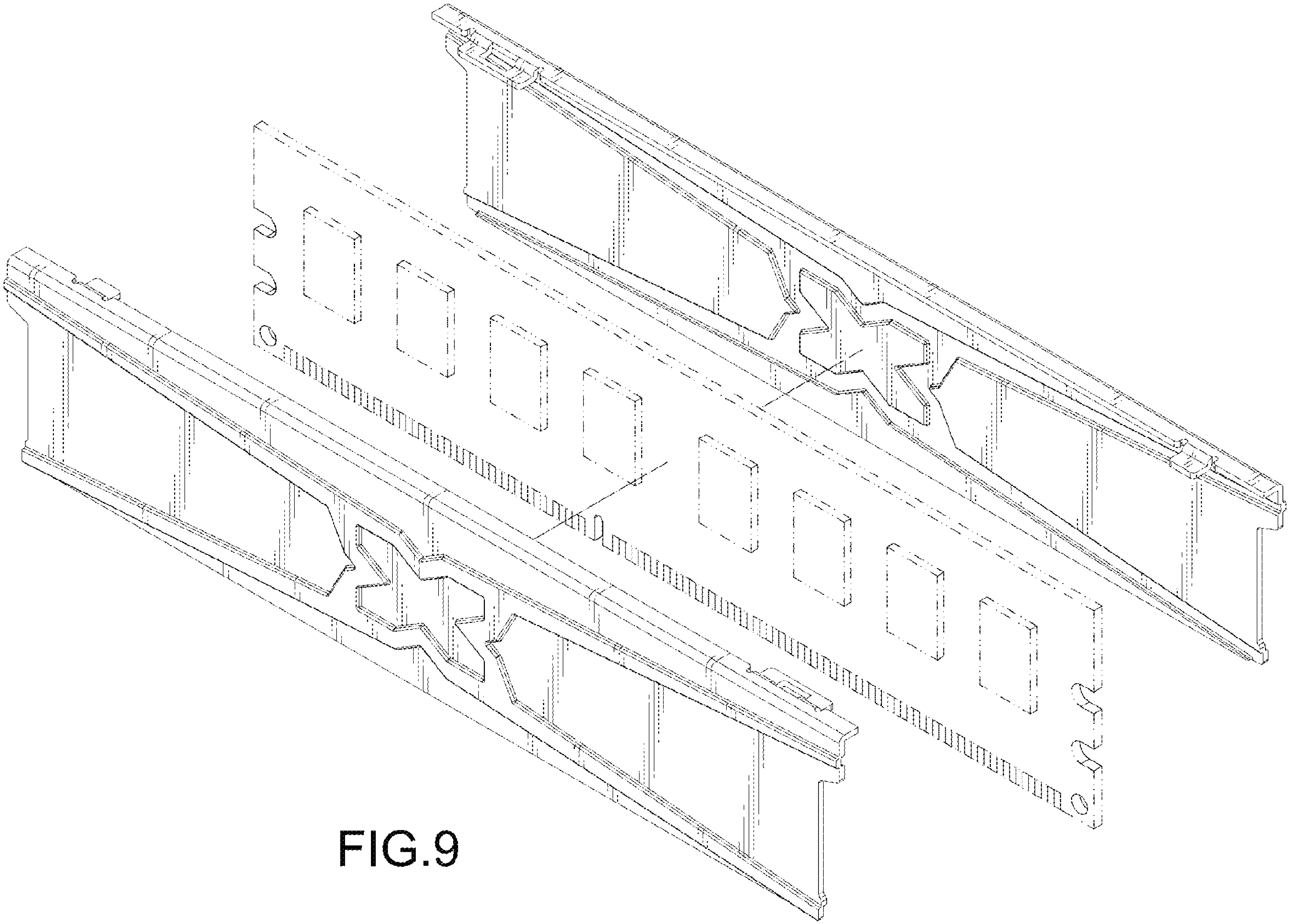


FIG.9